PIN Diode Drivers



Literature Number: SNVA531

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INTRODUCTION

The DH0035/DH0035C is a TTL/DTL compatible, DC coupled, high speed PIN diode driver. It is capable of delivering peak currents in excess of one ampere at speeds up to 10 MHz. This article demonstrates how the DH0035 may be applied to driving PIN diodes and comparable loads which require high peak currents at high repetition rates. The salient characteristics of the device are summarized in Table 1.

Parameter	Conditions	Value			
Differential Supply		30V Max.			
Voltage (V ⁺ – V ⁻)					
Output Current		1000 mA			
Maximum Power		1.5W			
t _{delay}	PRF = 5.0 MHz	10 ns			
t _{rise}	$V^{+} - V^{-} = 20V$	15 ns			
	10% to 90%				
t _{fall}	$V^{+} - V^{-} = 20V$	10 ns			
	90% to 10%				

TABLE 1. DH0035 Characteristics

PIN DIODE SWITCHING REQUIREMENTS

Figure 1 shows a simplified schematic of a PIN diode switch. Typically, the PIN diode is used in RF through microwave frequency modulators and switches. Since the diode is in shunt with the RF path, the RF signal is attenuated when the diode is forward biased ("ON"), and is passed unattenuated when the diode is reversed biased ("OFF"). There are essentially two considerations of interest in the "ON" condition. First, the amount of "ON" control current must be sufficient such that RF signal current will not significantly modulate the "ON" impedance of the diode. Secondly, the time required to achieve the "ON" condition must be minimized.

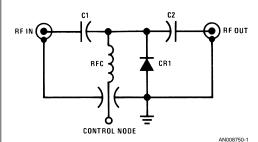


FIGURE 1. Simplified PIN Diode Switch

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(2)

The charge control model of a diode^{1,2} leads to the charge continuity equation given in *Equation (1)*.

$$= \frac{dQ}{dt} + \frac{Q}{\tau}$$
(1)

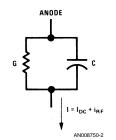
where: Q = charge due excess minority carriers τ = mean lifetime of the minority carriers

i

Equation (1) implies a circuit model shown in Figure 2. Under steady conditions $\frac{dQ}{dt} = 0$ hence:

dt
$$I_{DC} = \frac{Q}{\tau}$$
 or $Q = I_{DC} \bullet \tau$

where: I = steady state "ON" current.



I = Total Current

I_{DC} = SS Control Current i_{RF} = RF Signal Current

FIGURE 2. Circuit Model for PIN Switch

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The conductance is proportional to the current, I; hence, in order to minimize modulation due to the RF signal, $I_{DC} \geqslant i_{RF}$. Typical values for I_{DC} range from 50 mA to 200 mA depending on PIN diode type, and the amount of modulation that can be tolerated.

The time response of the excess charge, Q, may be evaluated by taking the Laplace transform of *Equation (1)* and solving for Q:

$$Q(s) = \frac{\tau I(s)}{1 + s\tau}$$
(3)

Solving Equation (3) for Q(t) yields:

$$Q(t) = L^{-1} [Q(s)] = I\tau (1 - e^{-t/\tau})$$
(4)

The time response of Q is shown in *Figure 3*. As can be seen, several carrier lifetimes are required to achieve the steady state "ON" condition $(Q = I_{DC} \bullet \tau)$.

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The time response of the charge, hence the time for the diode to achieve the "ON" state could be shortened by applying a current spike, lpk, to the diode and then dropping the current to the steady state value, I_{DC} , as shown in *Figure 4*. The optimum response would be dictated by:

(5)

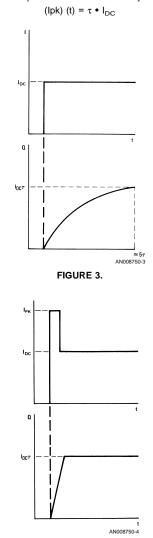


FIGURE 4.

The turn off requirements for the PIN diode are quite similar to the turn on, except that in the "OFF" condition, the steady current drops to the diode's reverse leakage current.

A charge, I_{DC} - $\tau,$ was stored in the diode in the "ON" condition and in order to achieve the "OFF" state this charge must

be removed. Again, in order to remove the charge rapidly, a large peak current (in the opposite direction) must be applied to the PIN diode:

$$lpk \gg \frac{Q}{\tau}$$
 (6)

It is interesting to note an implication of *Equation (5)*. If the peak turn on current were maintained for a period of time, say equal to τ , then the diode would acquire an excess charge equal to lpk • T. This same charge must be removed at turn off, instead of a charge $I_{DC} \bullet \tau$, resulting in a considerably slower turn off. Accordingly, control of the width of turn on current peak is critical in achieving rapid turn off.

APPLICATION OF THE DH0035 AS A PIN DIODE DRIVER

The DH0035 is specifically designed to provide both the current levels and timing intervals required to optimally drive PIN diode switches. Its schematic is shown in *Figure 5*. The device utilizes a complementary TTL input buffer such as the DM7830/DM8830 or DM5440/DM7440 for its input signals. Two configurations of PIN diode switch are possible: cathode grounded and anode grounded. The design procedures

for the two configurations will be considered separately.

ANODE GROUND DESIGN

Selection of power supply voltages is the first consideration. Table I reveals that the DH0035 can withstand a total of 30V differentially. The supply voltage may be divided symmetrically at \pm 15V, for example. Or asymmetrically at \pm 20V and -10V. The PIN diode driver shown in *Figure 6*, uses \pm 10V supplies.

When the Q output of the DM8830 goes high a transient current of approximately 50 mA is applied to the emitter of Q_1 and in turn to the base of Q_5 .

 Q_5 has an h_{fe} = 20, and the collector current is $h_{fe} x$ 50 or 1000 mA. This peak current, for the most part, is delivered to the PIN diode turning it "ON" (RF is "OFF").

lpk flows until C₂ is nearly charged. This time is given by:

$$t = \frac{C2\Delta V}{lpk}$$

(7)

where: ΔV = the change in voltage across C₂.

Prior to Q_5 's turn on, C_2 was charged to the minus supply voltage of -10V. C_2 's voltage will rise to within two diode drops plus a V_{sat} of ground:

$$V = |V^-| - Vf(PIN Diode) - Vf_{CR1} - V_{satQ5}$$
 (8)
- = -10V. $\Delta V = 8V$.

Once C_2 is charged, the current will drop to the steady state value, ${\rm I}_{\rm DC},$ which is given by:

$$I_{DC} = \frac{V}{R_{M}} - \frac{V^{+}}{R_{3}} - \frac{V_{CC}}{R_{1}}$$
(9)

here:
$$V_{CC} = 5.0V$$

 $R_1 = 250\Omega$

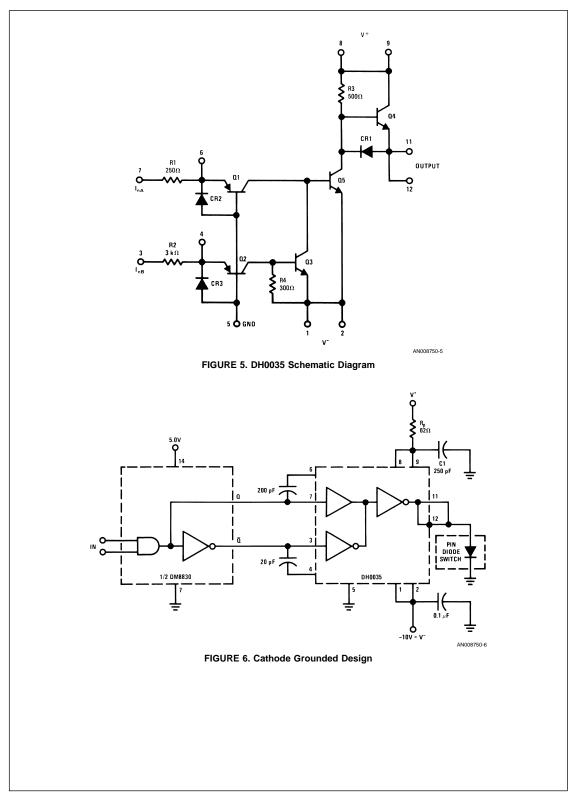
for V

w

$$R_3 = 500\Omega$$

$$\therefore R_{M} = \frac{(R_{3} (\Delta V) (R_{1}))}{R_{1}V^{+} + I_{DC}R_{3}R_{1} + V_{CC}R_{3}}$$
(10)

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For the driver of Figure 6, and I_{DC} = 100 mA, R_{M} is 56 Ω (nearest standard value).

Returning to *Equation (7)* and combining it with *Equation (5)* we obtain:

$$t = \frac{\tau I_{DC}}{Ipk} = \frac{C_2 V}{Ipk}$$
(11)

Solving Equation (11) for C₂ gives:

$$C_2 = \frac{I_{DC}\tau}{V}$$
(12)

For τ = 10 ns, C₂ = 120 pF.

One last consideration should be made with the diode in the "ON" state. The power dissipated by the DH0035 is limited to 1.5W (see Table I). The DH0035 dissipates the maximum power with Q_5 "ON". With Q_5 "OFF", negligible power is dissipated by the device. Power dissipation is given by:

$$\label{eq:point} \begin{split} \text{P diss} & \cong \left[\left| I_{\text{DC}} \left(\left| V^{-} \right| - \Delta V \right) + \frac{(V^{+} - V^{-})^{2}}{\text{R3}} \right] \\ & \times \left(\text{D.C.} \right) \leq \text{P}_{\text{max}} \end{split} \tag{13}$$

where: D.C. = Duty Cycle =

I

In terms of I_{DC}:

$$DC \leq \frac{\left[\frac{(Pmax)}{(D.C.)} - \frac{(V^+ - V^-)^2}{500}\right]}{|V^-| - \Delta V}$$
(14)

For the circuit of *Figure 6* and a 50% duty cycle, P diss = 0.5W.

Turn-off of the PIN diode begins when the Q output of the DM8830 returns to logic "0" and the \overline{Q} output goes to logic "1". Q₂ turns "ON", and in turn, causes Q₃ to saturate. Simultaneously, Q₁ is turned "OFF" stopping the base drive to Q₅.

 Q_3 absorbs the stored base charge of Q_5 facilitating its rapid turn-off. As $Q_5{}'s$ collector begins to rise, Q_4 turns "ON". At this instant, the PIN diode is still in conduction and the emitter of Q_4 is held at approximately –0.7V. The instantaneous current available to clear stored charge out of the PIN diode is:

$$lpk = \frac{V^{+} - V_{BEQ4} + V_{f(PIN)}}{\frac{R3}{h_{fe} + 1}}$$
$$\simeq \frac{(h_{fe} + 1)(V^{+})}{R_{3}}$$
(1)

where:

(15)

 h_{fe} + 1 = current gain of Q_4 = 20 V_{BE Q4} = base-emitter drop of Q_4 = 0.7V

 $V_{f(PIN)}$ = forward drop of the PIN diode = 0.7V

For typical values given, lpk = 400 mA. Increasing V⁺ above 10V will improve turn-off time of the diode, but at the expense of power dissipation in the DH0035. Once turn-off of the diode has been achieved, the DH0035 output current drops to the reverse leakage of the PIN diode. The attendant power dissipation is reduced to about 35 mW.

CATHODE GROUND DESIGN

Figure 7 shows the DH0035 driving a cathode grounded PIN diode switch. The peak turn-on current is given by:

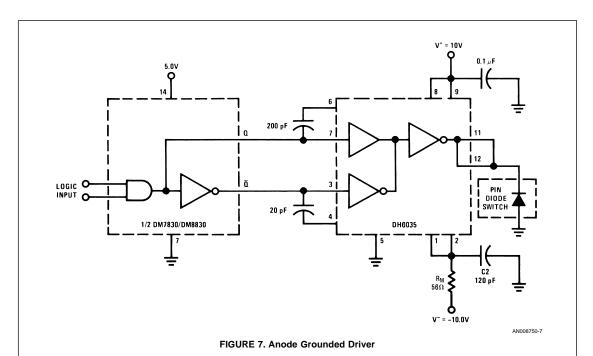
$$lpk \simeq \frac{(V^+ - V^-)(h_{fe} + 1)}{R3}$$
(16)

= 800 mA for the values shown.

The steady state current, $I_{\text{DC}},$ is set by Rp and is given by:

$$I_{DC} = \frac{(V^+ - 2V_{BE})}{\frac{R3}{h_{fe} + 1} + R_{P}}$$
(17)

where: $2V_{BE}$ = forward drop of Q_4 base emitter junction plus V_f of the PIN diode = 1.4V.



(18)

(21)

(22)

In terms of Rp, Equation (17) becomes:

$$Rp = \frac{(h_{fe} + 1)(V^+ - 2V_{BE}) - I_{DC}R_9}{(h_{fe} + 1)I_{DC}}$$

For the circuit of Figure 7, and $I_{\rm DC}$ = 100 mA, Rp is 62Ω (nearest standard value).

It now remains to select the value of C_1 . To do this, the change in voltage across C_1 must be evaluated. In the "ON" state, the voltage across C_1 , Vc, is given by:

$$(Vc)_{ON} = \frac{V^+ R_3 + Rp(h_{fe} + 1) (2V_{BE})}{R_3 + (h_{fe} + 1) Rp}$$
(19)

For the values indicated above, $(Vc)_{ON}$ = 3.8V. In the "OFF" state, Vc is given by:

$$(Vc)_{OFF} = \frac{V^+ R_3 - |V^-|Rp}{Rp + R_3}$$
(20)

= 8.0V for the circuit of Figure 7.

Hence, the change in voltage across $\ensuremath{C_1}$ is:

$$V = (Vc)_{OFF} - (Vc)_{ON}$$

= 8.0 - 3.8
= 4.2V

The value of C_4 is given, as before, by Equation (12):

$$C_1 = \frac{I_{DC}\tau}{V^-}$$

For a diode with τ = 10 ns and I_{DC} = 100 mA, C_1 = 250 pF. Again the power dissipated by the DH0035 must be considered. In the "OFF" state, the power dissipation is given by:

$$P_{OFF} = \left[\frac{V^+ - V^-)^2}{R_3}\right] (D.C.)$$
(23)

where: D.C. = duty cycle =

The "ON" power dissipation is given by:

$$\mathsf{P}_{\mathsf{ON}} = \left[\frac{(\mathsf{Vc})_{\mathsf{ON}}^2}{\mathsf{R}_3} + \mathsf{I}_{\mathsf{DC}} \times (\mathsf{Vc})_{\mathsf{ON}}\right] (1 - \mathsf{D.C.})$$

where: (Vc)_{ON} is defined by *Equation (19)*.

Total power dissipated by the DH0035 is simply $P_{ON} + P_{OFF}$. For a 50% duty cycle and the circuit of *Figure 7*, P diss = 616 mW.

The peak turn-off current is, as indicated earlier, equal to 50 mA x h_{fe} which is about 1000 mA. Once the excess stored charge is removed, the current through Q₅ drops to the diodes leakage current. Reverse bias across the diode = $V^- - V_{sat} \cong -10V$ for the circuit of *Figure 7*.

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(24)

REPETITION RATE CONSIDERATIONS

Although ignored until now, the PRF, in particular, the "OFF" time of the PIN diode is important in selection of C_2 , R_M , and C_1 , Rp. The capacitors must recharge completely during the diode "OFF" time. In short:

$4 R_M C_2 \le t_{OFF}$	(25)
$4 \text{ RpC}_{1} \leq t_{\text{OFF}}$	(26)

CONCLUSION

The circuit of *Figure 7* was breadboarded and tested in conjunction with a Hewlett-Packard 33622A PIN diode.

I_{DC} was set at 100 mA, V⁺ = 10V, V[−] = 10V. Input signal to the DM8830 was a 5V peak, 100 kHz, 5 μs wide pulse train. RF turn-on was accomplished in 10–12 ns while turn-off took approximately 5 ns, as shown in *Figure *NO TARGET FOR fig NS0292** and *Figure *NO TARGET FOR fig NS0292**.

In practice, adjustment C_2 (C_1) may be required to accommodate the particular PIN diode minority carrier lifetime.

SUMMARY

A unique circuit utilized in the driving of PIN diodes has been presented. Further a technique has been demonstrated which enables the designer to tailor the DH0035 driver to the PIN diode application.

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